

## **Concept 1: The "Green Computing" Initiative (Sustainability Focus)**

This concept focuses on **E-Waste Reduction** and **Refurbishment**. It turns the disassembly/assembly process into an environmental case study.

- **Project Title:** *Sustainable Tech: Optimizing Legacy Hardware for Extended Lifecycles.*
- **The Core Concept:** Investigating how strategic maintenance (disassembly/cleaning) and minor upgrades (assembly) can prevent electronic waste.
- **Target Audience:** Schools, non-profits, or budget-conscious offices.

### **Project Implementation Plan**

#### **1. Problem Statement**

"Electronic waste is a growing global issue. Many computers are discarded simply due to thermal throttling (dust buildup) or minor obsolescence (slow HDD), which can be resolved without buying a new system."

#### **2. Methodology**

- **Phase 1: Benchmarking (The Baseline):** Boot the existing old system. Run a benchmark (e.g., Cinebench, CrystalDiskMark). Record temperatures and boot times.
- **Phase 2: Disassembly (The Audit):**
  - Complete teardown of the system.
  - **Activity:** Deep cleaning of fans and heatsinks (demonstrating maintenance skills).
  - **Activity:** Inspecting capacitors on the motherboard for swelling (demonstrating diagnostic skills).
- **Phase 3: Component Upgrade (The Strategy):**
  - Replace the mechanical HDD with a cheap SATA SSD.
  - Repaste the CPU thermal compound.
- **Phase 4: Assembly (The Reconstruction):** Reassemble the system with the new drive and clean components. Cable manage for better airflow.
- **Phase 5: Re-Benchmarking:** Run the same tests. Compare the "Before" vs. "After" results.

#### **3. Conclusion/Result**

- *Data Point:* "Boot time reduced from 2 minutes to 15 seconds."
- *Data Point:* "CPU temperature reduced by 10°C due to cleaning and re-pasting."

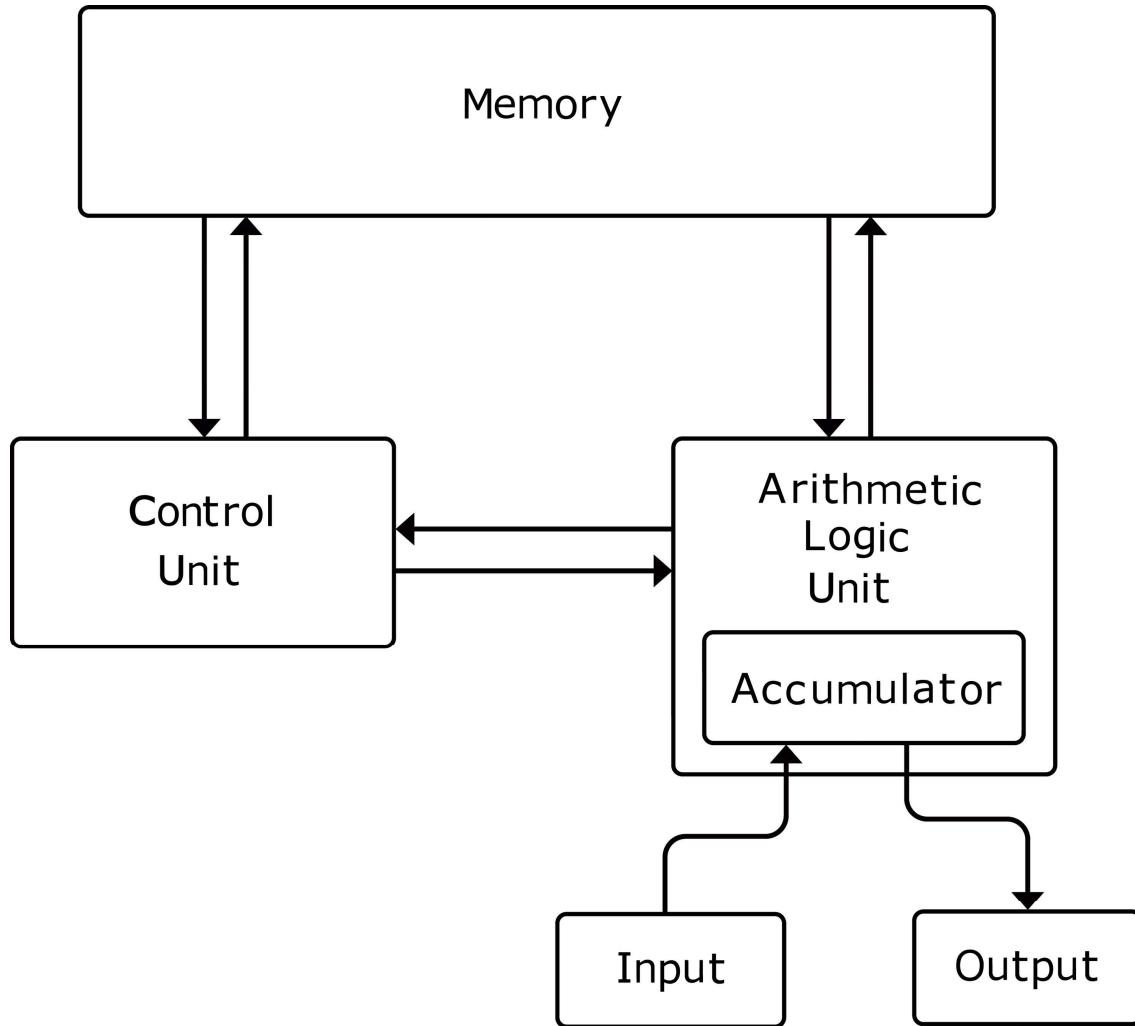
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## **Concept 2: The "Von Neumann Architecture" Study (Theoretical Focus)**

This concept connects the physical hardware to standard Computer Science theory. It turns the build into an educational anatomy lesson.

- **Project Title:** *Physical Implementation of the Von Neumann Architecture.*

- **The Core Concept:** Mapping physical components to the theoretical "Five Components of Computer Organization" (Input, Output, Memory, Datapath, Control).



#### Project Implementation Plan

1. **Objective** To demonstrate how modern hardware physically instantiates the abstract Von Neumann model.
2. **Methodology (The Mapping)** In your project report, you do not just list "RAM"; you classify it by its architectural function.
  - **Disassembly Phase:** As you remove parts, categorize them:
    - *Removal of SSD:* "Removing Secondary Storage (Non-volatile memory)."
    - *Removal of CPU:* "Removing the Central Processing Unit (ALU + Control Unit)."
  - **Assembly Phase:** Build the system in the order of "Data Flow."
    1. **Motherboard (Bus System):** The communication highway.
    2. **CPU (Processing):** The brain.

3. **RAM (Primary Memory):** The workspace.

4. **I/O Devices:** The peripherals.

**3. Analysis** Explain how the "Bottleneck" works. (e.g., "The CPU (Control Unit) processes data faster than the HDD (Storage) can supply it, demonstrating the Von Neumann bottleneck.")

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### **Concept 3: The "Thermal Dynamics" Study (Engineering Focus)**

This concept focuses on physics and cooling efficiency.

- **Project Title:** *Impact of Cable Management and Airflow Pressure on System Stability.*
- **The Core Concept:** Comparing a "messy" build vs. a "clean" build to see how physical assembly affects hardware longevity.

#### **Project Implementation Plan**

##### **1. Methodology**

- **Build A (The Control):** Assemble the computer with messy cables blocking airflow. Close the case. Stress test for 30 mins. Record peak CPU/GPU temps.
- **Disassembly:** Take it apart.
- **Build B (The Variable):** Reassemble with strict cable management (zip ties) and optimal fan orientation (Positive vs. Negative pressure).
- **Test:** Run the same stress test.

**2. Conclusion** Demonstrate that *skillful* assembly (not just connecting parts, but managing them) results in lower temperatures and higher boost clocks.